

A PRINTED WIRING BOARD HAVING A DISCONTINUOUS
PLATING LAYER AND METHOD OF MANUFACTURE THEREOF

ABSTRACT OF THE DISCLOSURE

The present invention provides a method of plating an electrical contact on an integrated circuit (IC) substrate manufactured from a rigid double-sided or multi-layered printed wiring board core with dielectric layers on both sides of the core. The method may include forming electrically connected plating layers on first and second opposing sides of a substrate and electroplating a contact layer over each of the plating layers using the plating layers. The method further includes removing a portion of the plating layers from the first and second opposing sides while leaving the plating layers under the contact layer.

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